AUTOMOTIVE GRADE

RoHS

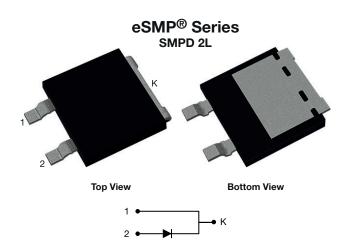
COMPLIANT

HALOGEN FREE



Vishay General Semiconductor

Surface-Mount Low V_F Standard Rectifiers



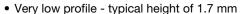
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I _{F(AV)}	12 A			
V_{RRM}	400 V, 600 V			
I _{FSM}	165 A			
V_F at $I_F = 12 \text{ A } (T_J = 125 \text{ °C})$	0.83 V			
T_J max.	175 °C			
Package	SMPD 2L			
Circuit configuration	Single			

FEATURES

• Creepage and clearance distance 3.7 mm



- Low forward voltage drop
- · Ideal for automated placement
- · Oxide planar chip junction
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	SE12DTLG	SE12DTLJ	UNIT	
Device marking code		SE12DTLG	SE12DTLJ		
Maximum repetitive peak reverse voltage		400	600	V	
Maximum DC forward current	I _F ⁽¹⁾	12		А	
	I _F ⁽²⁾	3.6			
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}	165		А	
Operating junction and storage temperature range	T _J , T _{STG} ⁽³⁾	-55 to +175		°C	

Notes

- (1) Mounted on infinite heatsink
- (2) Free air, mounted on recommended copper pad area
- $^{(3)}$ The heat generated must be less than the thermal conductivity from junction to ambient $dP_D/dT_J < R_{thJA}$

SE12DTLG, SE12DTLJ

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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 6 A	T _J = 25 °C		0.86	-	V
	I _F = 12 A		V _E ⁽¹⁾	0.93	1	
	I _F = 6 A	- T _J = 125 °C	VF (*)	0.72	-	
	I _F = 12 A			0.83	0.9	
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	-	5	- μΑ
	naleu v _R	T _J = 125 °C	IR (=)	12	70	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	300	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	96	-	pF

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Typical thermal resistance	R _{θJA} (1)(2)	57	71	°C/W	
	R _{0JM} (3)	1.5	1.8		

Notes

- $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Free air, mounted on recommended PCB, 2 oz. pad area; thermal resistance R_{0JA} junction to ambient to follow JEDEC® 51-2A
- (3) Mounted on infinite heatsink thermal resistance R_{thJM} junction to mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)					
PREFERRED P/N	PREFERRED P/N UNIT WEIGHT (g) PREFERRED PACKAGE CODE BASE QUANTIT		BASE QUANTITY	DELIVERY MODE	
SE12DTLJ-M3/I	0.51	1	2000/reel	13" diameter plastic tape and reel	
SE12DTLJHM3/I (1)	0.51	1	2000/reel	13" diameter plastic tape and reel	

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

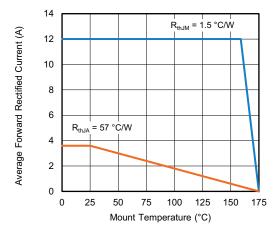


Fig. 1 - Forward Current Derating Curve

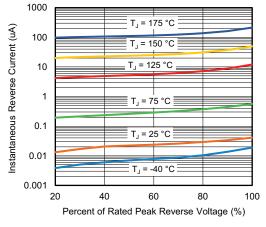


Fig. 4 - Typical Reverse Leakage Characteristics

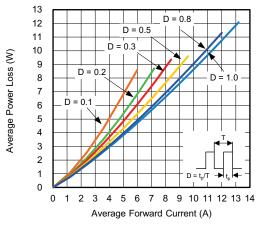


Fig. 2 - Forward Power Loss Characteristics

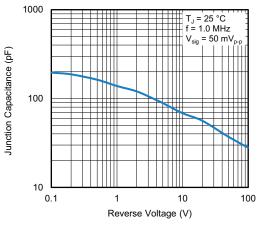


Fig. 5 - Typical Junction Capacitance

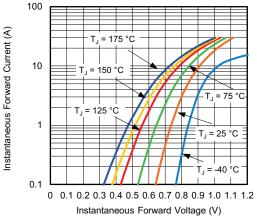


Fig. 3 - Typical Instantaneous Forward Characteristics

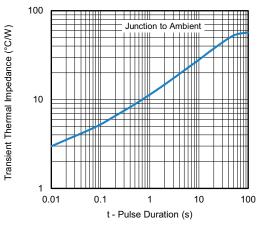


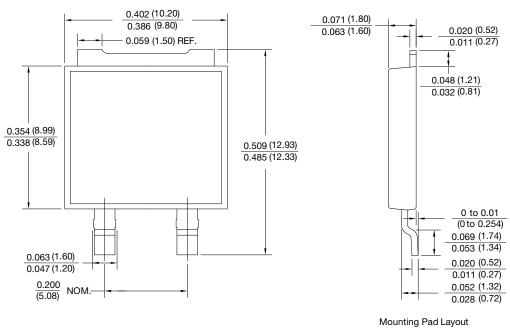
Fig. 6 - Typical Transient Thermal Impedance

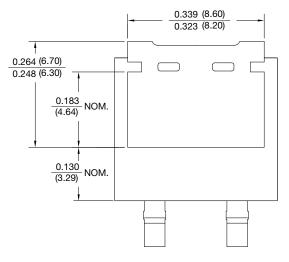


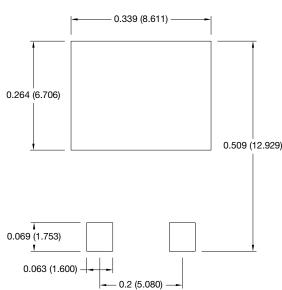
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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)









Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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